

/ Descriptions

SOD-523

Schottky Diode in a SOD-523 Plastic Package.

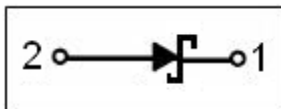
/ Features

Low forward voltage drop,HF Product.

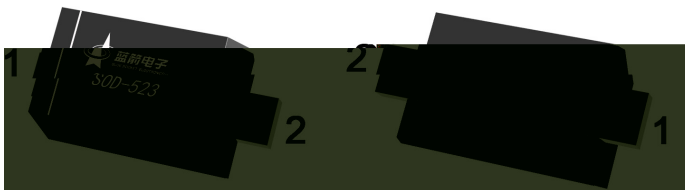
/ Applications

General purpose.

/ Equivalent Circuit



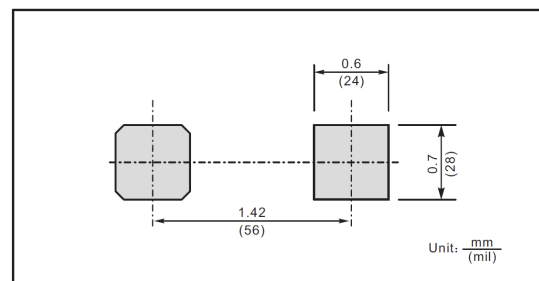
/ Pinning



PIN1: Cathode

PIN2: Anode

The recommended mounting pad size



/ Marking

Type number	Marking code
RB521S-30	C

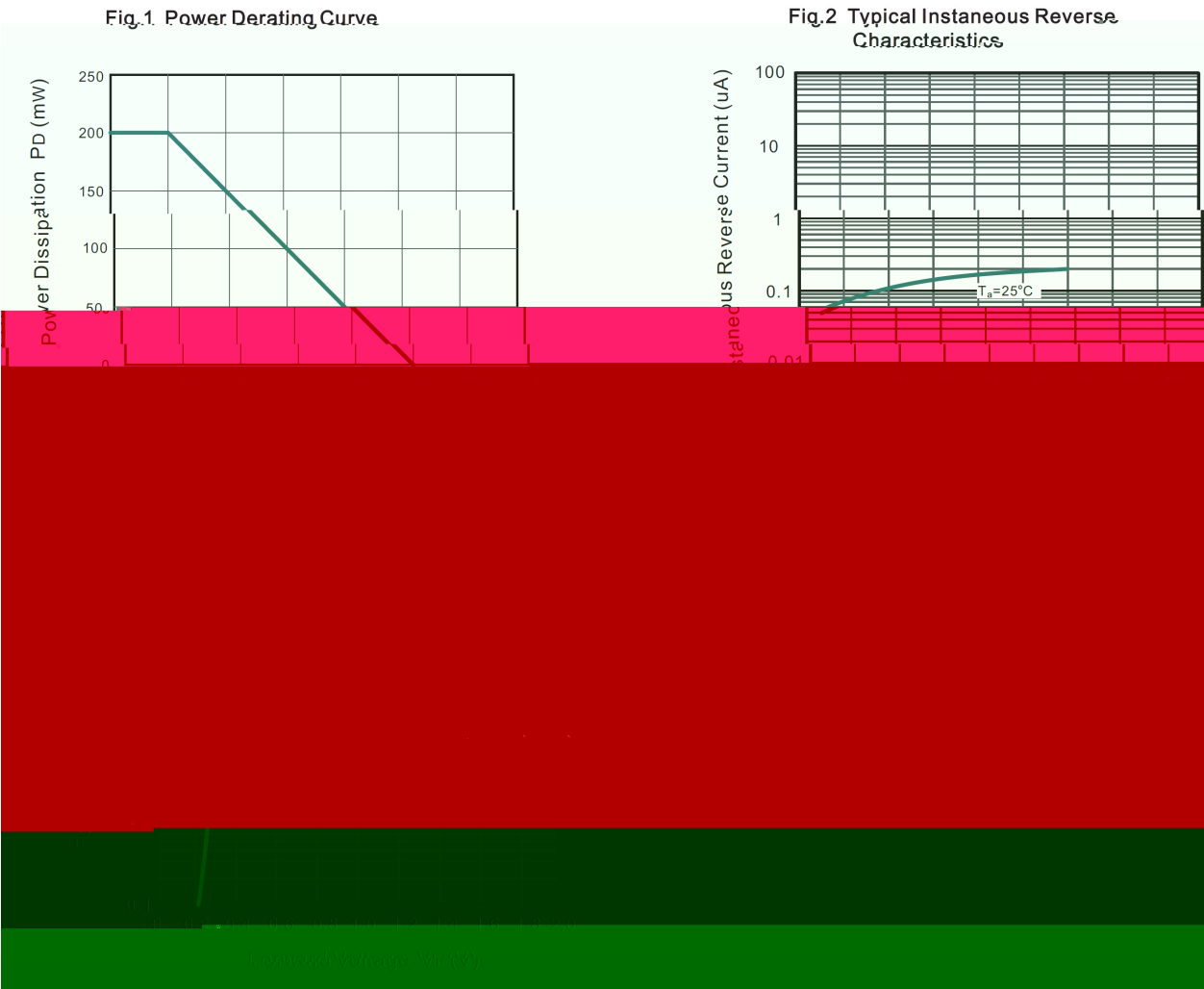
/ Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	30	V
Forward Continuous Current	I_F	200	mA
Non-Repetitive Peak Forward Surge Current @ $t = 8.3\text{ms}$	I_{FSM}	1	A
Power dissipation	P_D	200	mW
Junction Temperature	T_J	125	
Storage Temperature	T_{stg}	-55 to +125	

/ Electrical Characteristics($T_a=25^\circ\text{C}$)

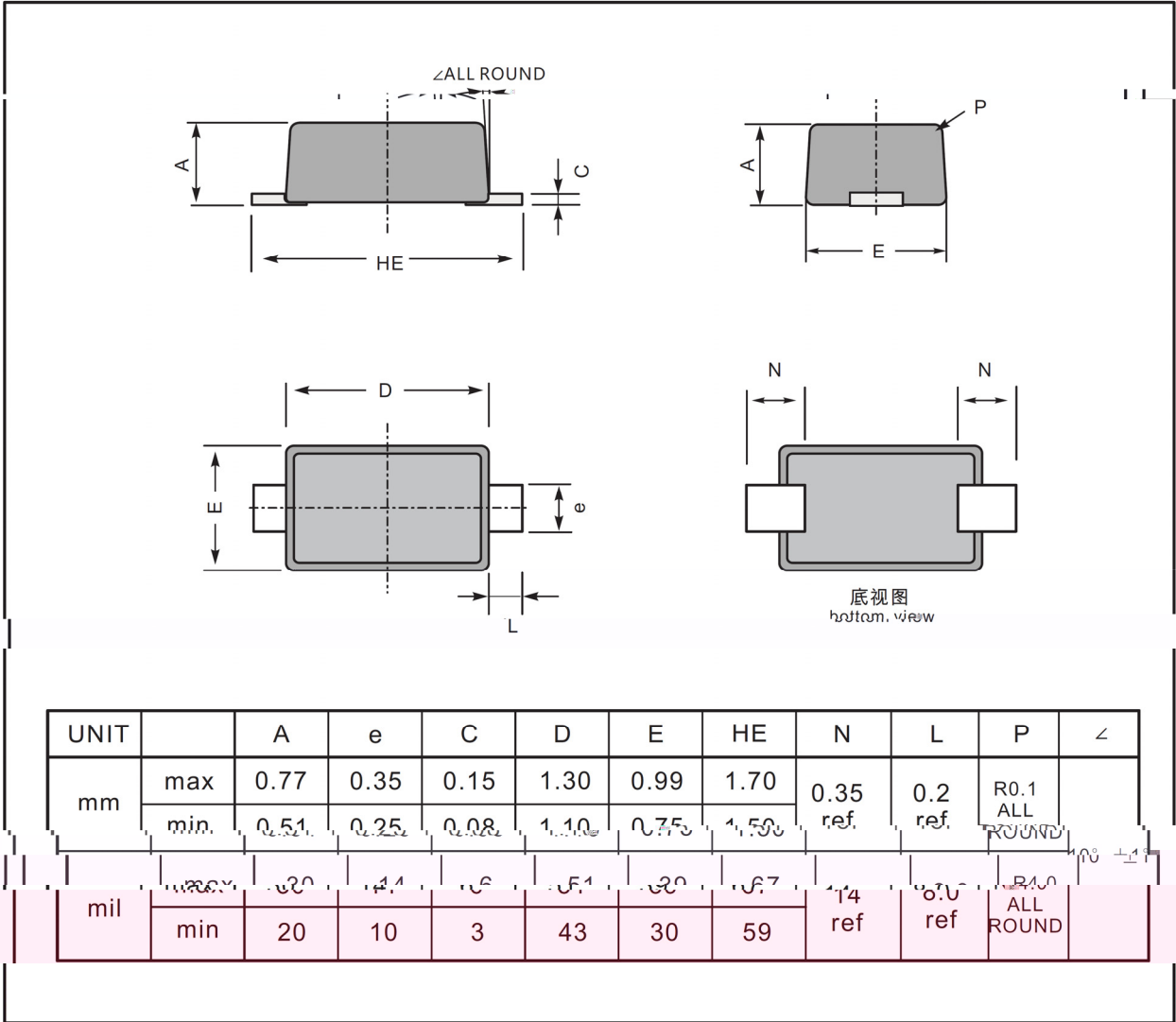
Parameter	Symbol	Test Conditions	Rating			Unit
			Min	Typ	Max	
Reverse Breakdown Voltage	V_{BR}	$I_R=500\mu\text{A}$	30			V
Forward Voltage	V_F	$I_F=20\text{mA}$			0.37	V
		$I_F=200\text{mA}$			0.60	V
Peak Reverse Current	I_R	$V_R=10\text{V}$			5.0	A

/ Electrical Characteristic Curve

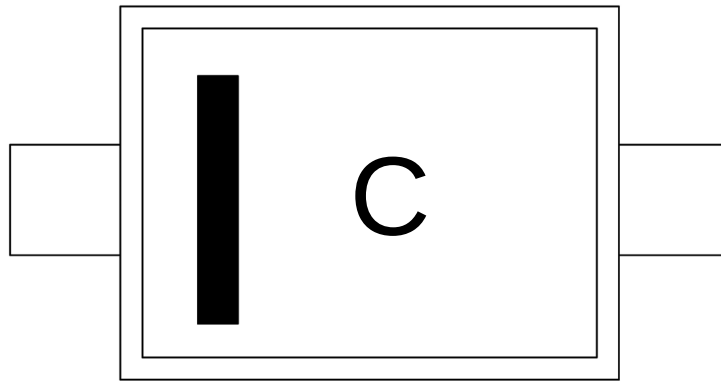


/ Package Dimensions

SOD-523



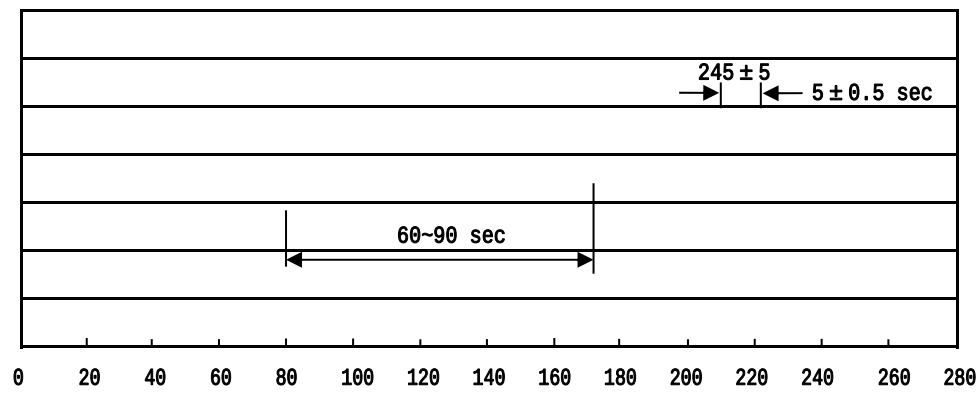
/ Marking Instructions



Note:

C : Product Type Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245 5

5 0.5sec;

2.Peak Temp.:245 5 , Duration:5 0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱
SOD-523	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices